

SOT823-1

plastic low profile quad flat package; 80 leads; body 14 x 14 x 1.4 mm

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	LQFP80
Package type industry code	LQFP80
Package style descriptive code	LQFP (low profile quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
IEC package outline code	136E19
JEDEC package outline code	MS-026
Mounting method type	S (surface mount)
Issue date	15-7-2003

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		13.9	-	14	14.1	mm
E	package width		13.9	-	14	14.1	mm
A	seated height		[tbd]	-	1.6	1.6	mm
A ₂	package height		1.35	-	1.4	1.45	mm
n ₂	actual quantity of termination		-	-	80	-	



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2. Package outline

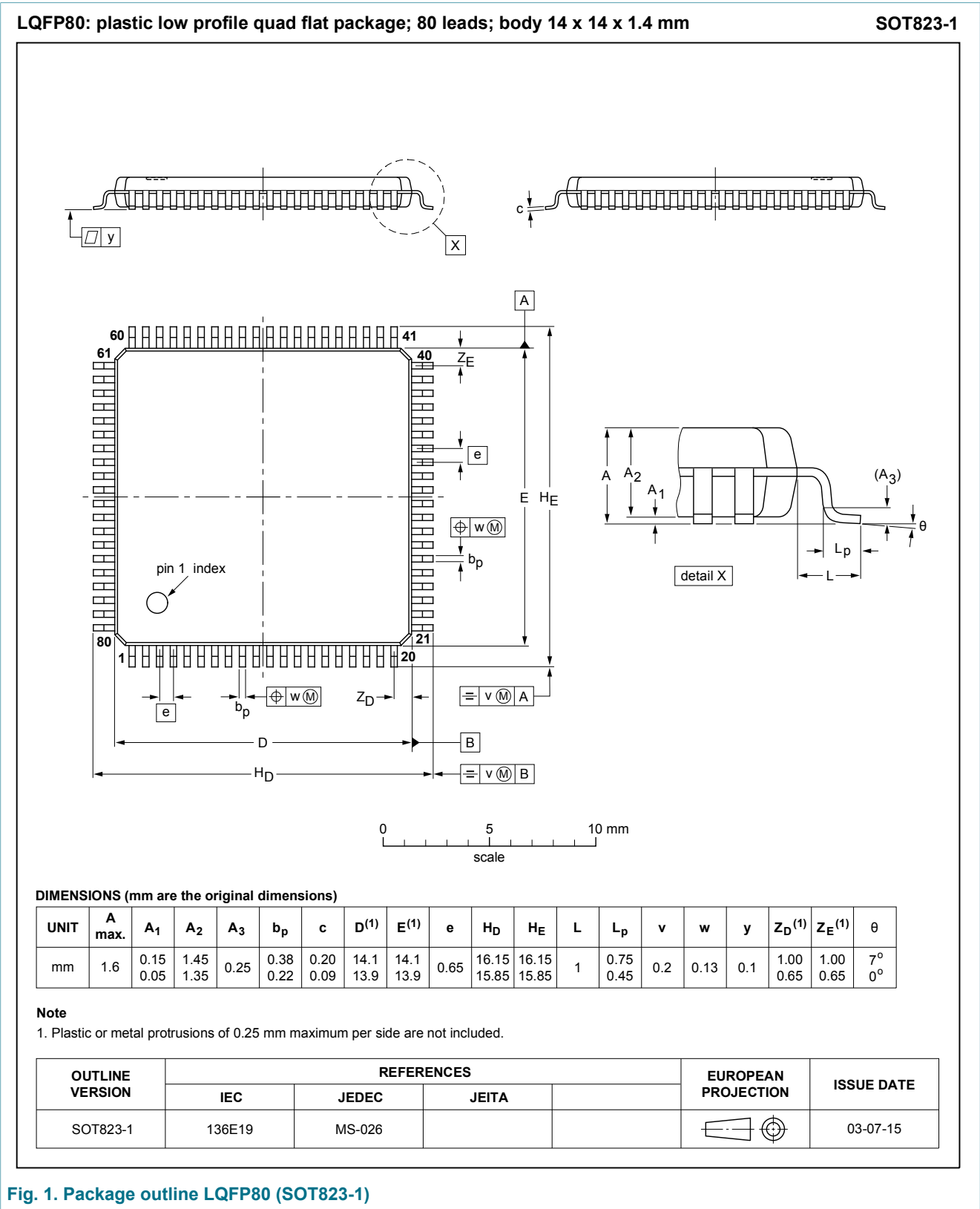


Fig. 1. Package outline LQFP80 (SOT823-1)

3. Soldering

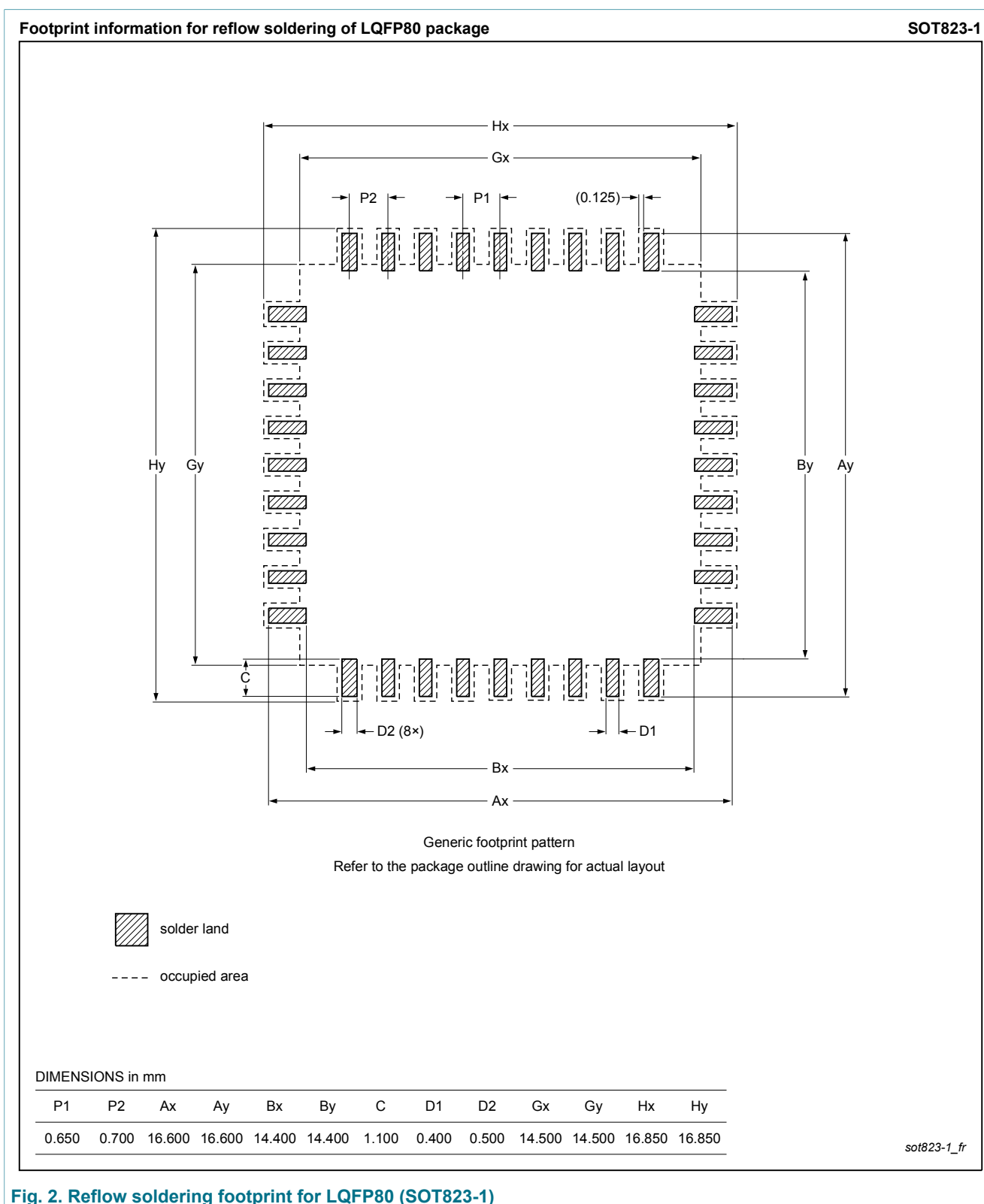


Fig. 2. Reflow soldering footprint for LQFP80 (SOT823-1)

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4. Legal information

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